

N-Channel Enhancement Mode Power MOSFET

● Features

$V_{DS} = 30V$

$I_D = 28A$

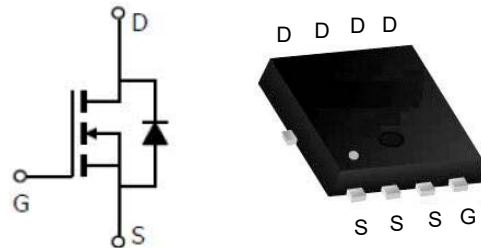
$R_{DS(ON)} \leq 18m\Omega (V_{GS}=10V)$

● General Description

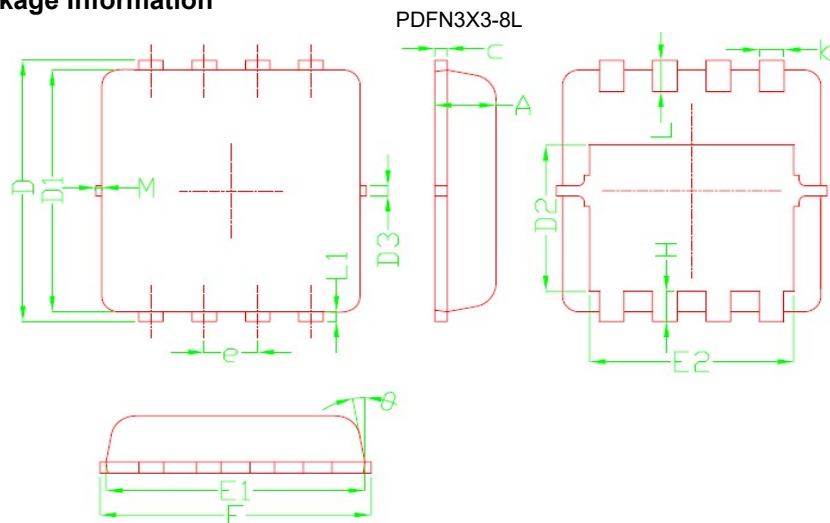
The TNM2030N3X is the high cell density trench N-ch MOSFETs, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The TNM2030N3X meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

● Pin Configurations



● Package Information



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.85	0.027	0.034
b	0.20	0.40	0.007	0.016
c	0.10	0.25	0.004	0.010
D	3.15	3.45	0.124	0.136
D1	2.90	3.20	0.114	0.126
D2	1.54	1.98	0.060	0.080
D3	0.10	0.30	0.004	0.012
E	3.15	3.45	0.124	0.136
E1	3.00	3.25	0.118	0.128
E2	2.29	2.65	0.090	0.104
e	0.65 BSC		0.025 BSC	
H	0.28	0.65	0.011	0.026
Θ	0°	14°	0°	14°
L	0.30	0.50	0.012	0.020
L1	0.13		0.005	
M	---	0.15	---	0.006



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● Absolute Maximum Ratings (@TA=25°C unless otherwise noted)

Parameter		Symbol	Ratings	Unit
Drain-Source Voltage		V_{DSS}	30	V
Gate Source Voltage		V_{GSS}	±20	V
Drain Current (Continuous) *AC	TA=25°C	I_D	28	A
	TA=100°C		18	
Drain Current (Pulse) *B		I_{DM}	55	A
Power Dissipation	TA=25°C	P_D	20	W
Operating Temperature/ Storage Temperature		T_J/T_{STG}	-55~150	°C
Single Pulse Avalanche Energy		E_{AS}	22.1	mJ
Avalanche Current		I_{AS}	21	A

● Thermal Characteristics

Parameter	Symbol	Ratings	Unit
Thermal Resistance ,Junction-to-Ambient	$R_{\theta JA}$	75	°C/W
Thermal resistance, junction-case max	$R_{\theta JC}$	6	°C/W

● Electrical Characteristics (@TA=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=24V, V_{GS}=0V$	--	--	1	μA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	1.0	--	2.5	V
Gate Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	±100	nA
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=10A$	--	--	18	mΩ
		$V_{GS}=4.5V, I_D=5A$	--	--	30	mΩ
Forward Transconductance	g_{fs}	$I_{SD}=1A, V_{DS}=5V$	--	4.5	--	S
Total Gate Charge	Q_g	$V_{GS}=4.5V, V_{DS}=20V, I_D=10A$	--	7.2	--	nC
Gate- Source Charge	Q_{gs}		--	1.4	--	nC
Gate- Drain Charge	Q_{gd}		--	2.2	--	nC
Turn-on Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DD}=12V, I_D=5A, R_{GEN}=3.3\Omega$	--	4.1	--	ns
Turn-on Rise Time	t_r		--	9.8	--	ns
Turn-off Delay Time	$t_{d(off)}$		--	15.5	--	ns
Turn-off Fall Time	t_f		--	6.0	--	ns
Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=15V, f=1MHz$	--	572	--	pF
Output Capacitance	C_{oss}		--	81	--	pF
Reverse Transfer Capacitance	C_{rss}		--	65	--	pF

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● Reverse Diode Characteristics (@TA=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Continuous Diode Forward Current	IS	VG=VD=0V , Force Current	--	--	28	A
Diode Forward Voltage	VSD	ISD=1A, VGS=0V	--	--	1.2	V

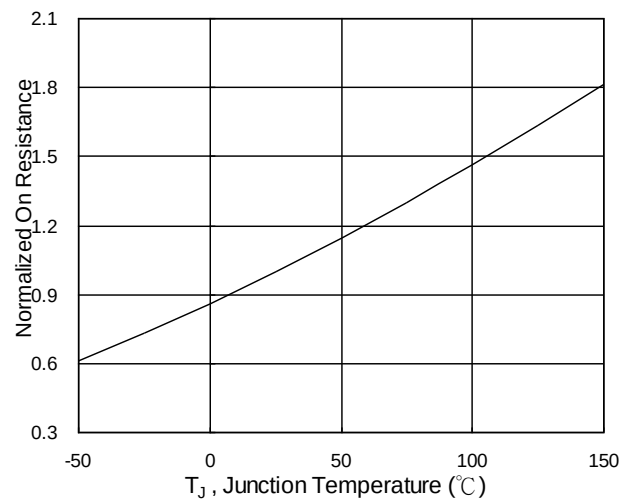
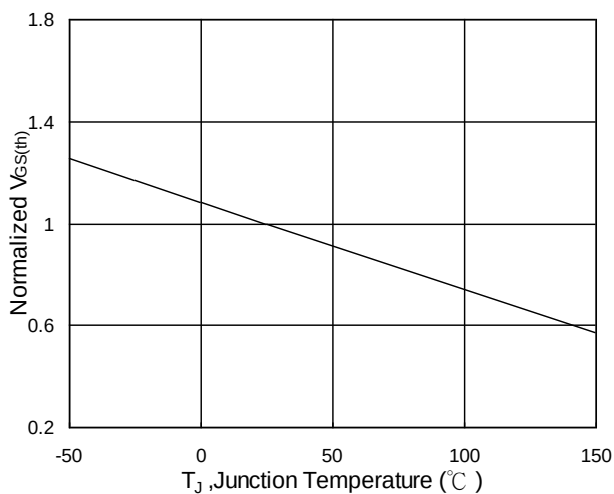
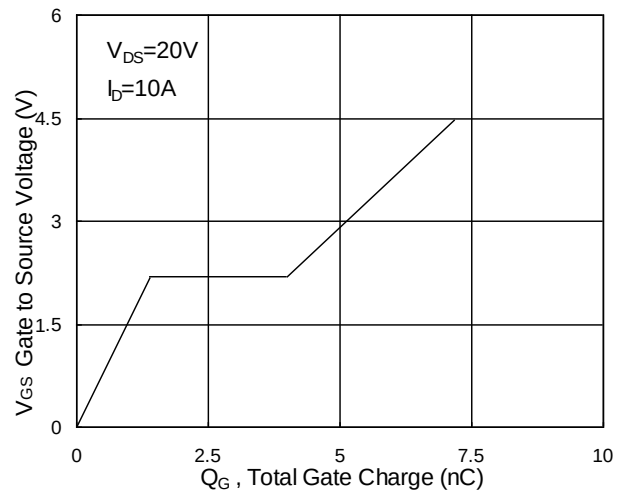
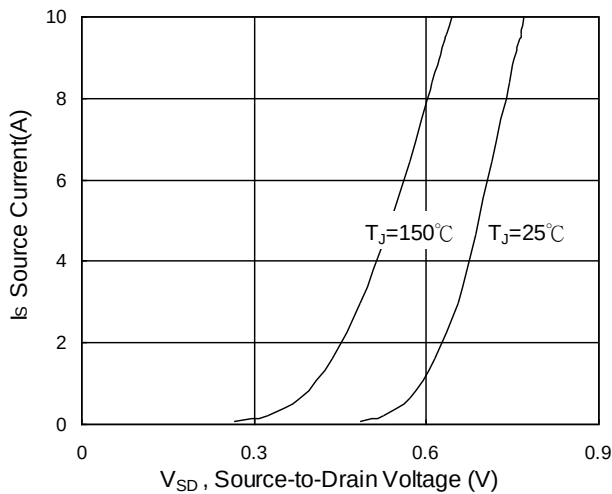
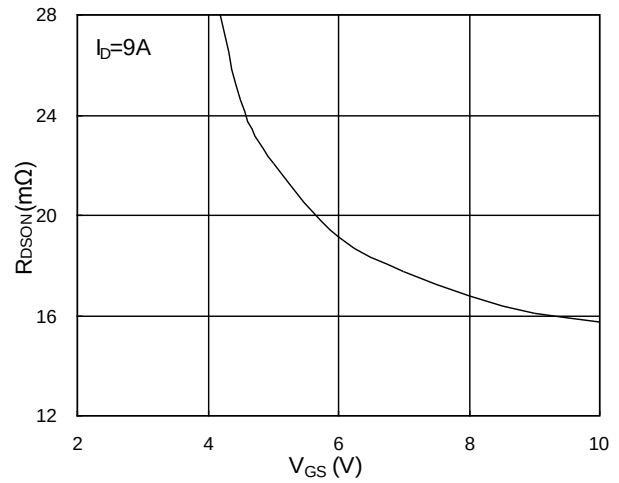
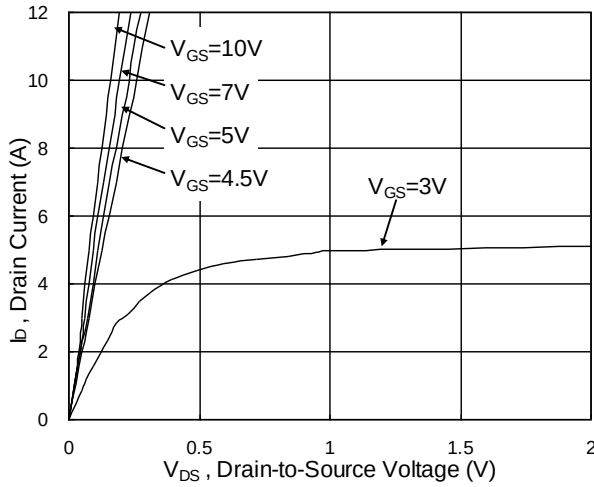
A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in2 FR- 4 board with 2oz. Copper, in a still air environment with TA=25C. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature .

C: The current rating is based on the $t < 10s$ junction to ambient thermal resistance rating.

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● TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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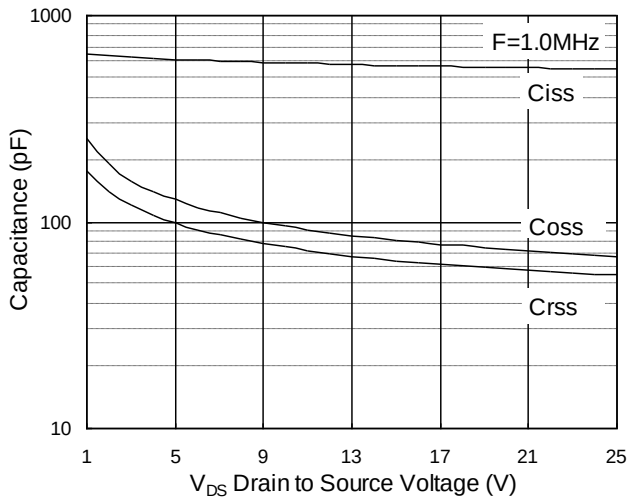


Fig.7 Capacitance

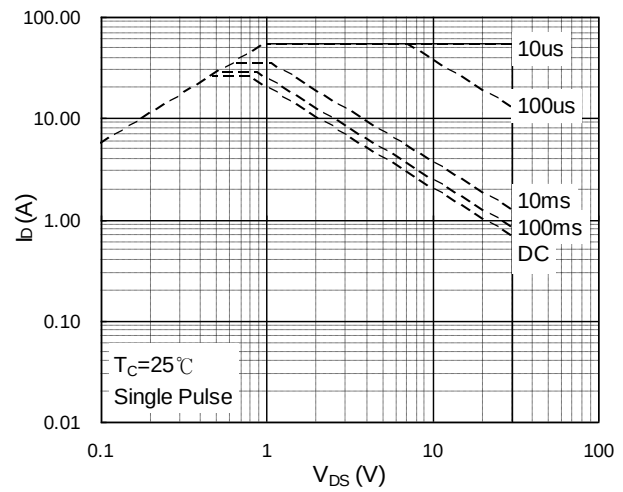


Fig.8 Safe Operating Area

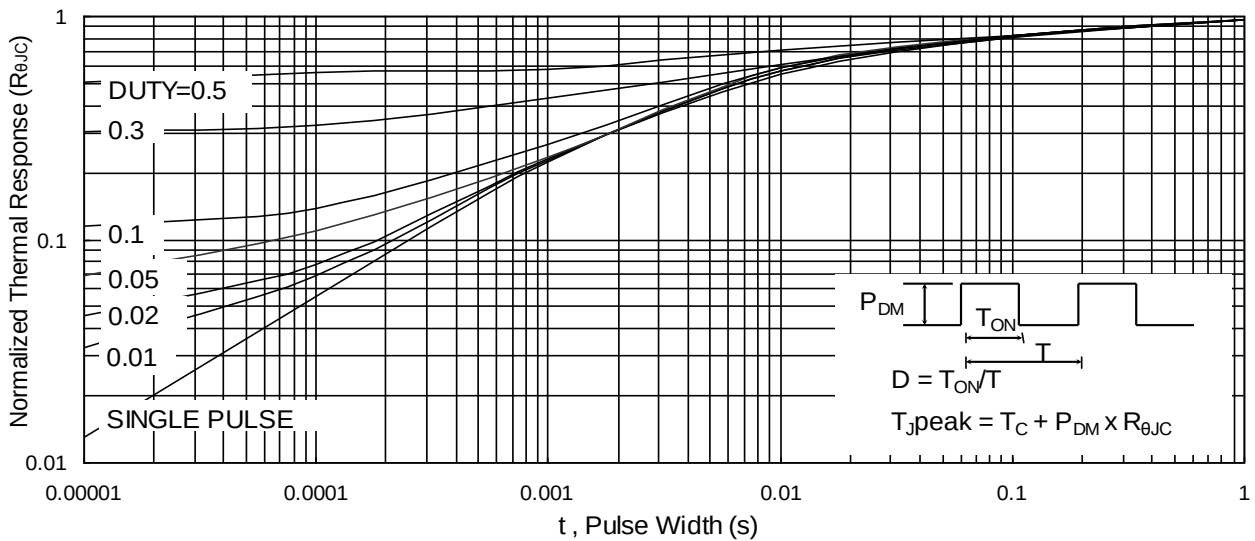


Fig.9 Normalized Maximum Transient Thermal Impedance

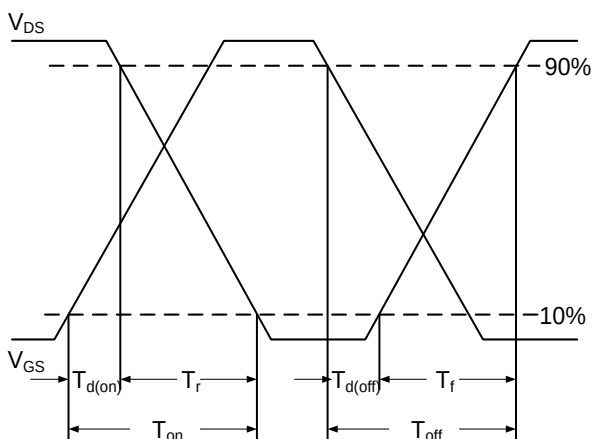


Fig.10 Switching Time Waveform

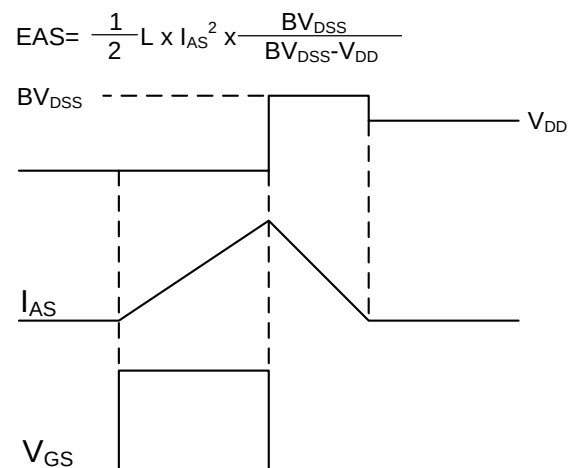


Fig.11 Unclamped Inductive Waveform